

Listing of the Claims:

This listing of claims will replace all previous versions of the claims:

1-3. (Cancelled)

4. (Currently Amended) A thin-film capacitor element comprising:
an insulative substrate having a via hole filled with a conductive
material;
a lower electrode;
a dielectric layer; and
an upper electrode;
wherein the lower electrode, the dielectric layer on the lower
electrode, and the upper electrode on the dielectric layer are disposed on the
insulative substrate, at least a portion of the upper and lower electrodes
overlap with the dielectric layer therebetween in a direction perpendicular to a
face of the substrate,
~~either one of the lower electrode and the upper electrode~~
connects to an end face of the conductive material in an area not having a
dielectric layer; and
the dielectric layer is shaped like a ring to surround the via hole.

5. (Previously Presented) A thin-film capacitor element according to
Claim 4, wherein an area between the dielectric layer and the via hole is ring
shaped.

6. (Previously Presented) A thin-film capacitor element according to
Claim 4, wherein the insulative substrate is made of low-temperature-sintered
ceramic.

7-9. (Cancelled)

10. (Currently Amended) A thin-film capacitor element according to
Claim 94, wherein the entire circumference of the lower electrode is not
covered by the dielectric layer and the entire circumference of the dielectric
layer is not covered by the upper electrode.

11. (Currently Amended) A thin-film capacitor element according to
Claim 94, wherein the lower electrode and a portion of the upper electrode
surrounding the area that connects to the end face of the conductive material
contact the insulative substrate.

12. (Previously Presented) A thin-film capacitor element according to
Claim 11, wherein the dielectric layer is disposed on the insulative substrate
between the lower electrode and the portion of the upper electrode that
contacts the insulative substrate.